

General Description

The WSF40P04 is the highest performance trench P-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSF40P04 meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

Product Summery

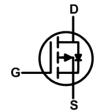
| BVDSS | RDSON | ID |
|-------|-------|------|
| -40V | 32mΩ | -20A |

Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

TO-252-3L(D-PAK) Pin Configuration





Absolute Maximum Ratings

| Symbol Parameter | | Rating | Units |
|----------------------------------------------------------------------------|--------------------------------------------------------------------------|------------|-------|
| V _{DS} | Drain-Source Voltage | -40 | V |
| V _{GS} | Gate-Source Voltage | ±20 | V |
| I _D @T _C =25°C | Continuous Drain Current, V _{GS} @ -10V ¹ | -20 | Α |
| I _D @T _C =100℃ | Continuous Drain Current, V _{GS} @ -10V ¹ | -16 | Α |
| I _{DM} | Pulsed Drain Current ² | -28 | Α |
| I _{AR} | Avalanche Current | -22 | А |
| EAR | EAR Repetitive avalanche energy L=0.1mH | | mJ |
| EAS Single pulse avalanche energy L=0.3mH | | 55 | mJ |
| P _D @T _C =25°C | P _D @T _C =25℃ Total Power Dissipation ⁴ | | W |
| P _D @T _C =100 ℃ Total Power Dissipation ⁴ | | 20 | W |
| P _D @T _A =25℃ | P _D @T _A =25℃ Power Dissipation ^A | | W |
| P _D @T _A =70°C | Power Dissipation ^A | 1.5 | W |
| T _J T _{STG} | Junction and Storage Temperature Range | -55 to 175 | °C |

Thermal Data

| Symbol | Parameter | | Max. | Unit |
|------------------|-----------------------------------------------------------|--|------|------|
| $R_{\theta JA}$ | Thermal Resistance Junction-Ambient ¹ | | 50 | °C/W |
| $R_{	heta JA}$ | Thermal Resistance Junction-Ambient ¹ (t ≤10s) | | 25 | °C/W |
| R _{θJC} | Thermal Resistance Junction-Case ¹ | | 2.5 | °C/W |



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Unit |
|--------------------------------------|------------------------------------------------|----------------------------------------------------------------------|------|---------|------|------|
| BV _{DSS} | Drain-Source Breakdown Voltage | V_{GS} =0V , I_D =-250uA | -40 | | | V |
| $\triangle BV_{DSS}/\triangle T_{J}$ | BVDSS Temperature Coefficient | Reference to 25℃, I _D =-1mA | | -0.0232 | | V/°C |
| D | Static Drain-Source On-Resistance ² | V _{GS} =-10V , I _D =-12A | | 32 | 42 | 0 |
| $R_{DS(ON)}$ | | V _{GS} =-4.5V , I _D =-8A | | 52 | 58 | mΩ |
| V _{GS(th)} | Gate Threshold Voltage | | -1 | -2 | -3 | V |
| $\triangle V_{GS(th)}$ | V _{GS(th)} Temperature Coefficient | V _{GS} =V _{DS} , I _D =-250uA | | 4.6 | | mV/℃ |
| | Drain Source Lookage Current | V _{DS} =-32V , V _{GS} =0V , T _J =25℃ | | | -1 | - uA |
| I _{DSS} | Drain-Source Leakage Current | V_{DS} =-32V , V_{GS} =0V , T_{J} =55 $^{\circ}$ C | | | -5 | uA |
| I _{GSS} | Gate-Source Leakage Current | V_{GS} = $\pm 20 V$, V_{DS} = $0 V$ | | | ±100 | nA |
| gfs | Forward Transconductance | V _{DS} =-5V , I _D =-12A | | 10 | | S |
| Rg | Gate Resistance | V _{DS} =0V , V _{GS} =0V , f=1MHz | | 6.0 | | Ω |
| Qg | Total Gate Charge (-4.5V) | | | 20 | | |
| Q_{gs} | Gate-Source Charge | V _{DS} =-20V , V _{GS} =-10V , I _D =-15A | | 2.5 | | nC |
| Q_gd | Gate-Drain Charge | | | 4.5 | | |
| T _{d(on)} | Turn-On Delay Time | | | 5 | | |
| T _r | Rise Time | V _{DD} =-20V , V _{GS} =-10V , | | 12 | | |
| T _{d(off)} | Turn-Off Delay Time | R_G =1.6 Ω | | 20 | | ns |
| T _f | Fall Time | | | 4.5 | | |
| C _{iss} | Input Capacitance | | | 840 | | |
| C _{oss} | Output Capacitance | V _{DS} =-25V , V _{GS} =0V , f=1MHz | | 92 | | pF |
| C _{rss} | Reverse Transfer Capacitance | | | 60 | | |

Diode Characteristics

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Unit |
|-----------------|------------------------------------------|-----------------------------------------------------------------|------|------|------|------|
| Is | Continuous Source Current ^{1,6} | // =// =0// Force Current | | | -10 | Α |
| I _{SM} | Pulsed Source Current ^{2,6} | V _G =V _D =0V , Force Current | | | -20 | Α |
| V_{SD} | Diode Forward Voltage ² | V _{GS} =0V , I _S =-1A , T _J =25℃ | | | -1 | V |
| t _{rr} | Reverse Recovery Time | I- 404 II/II 4004/ | | 20 | | nS |
| Qrr | Reverse Recovery Charge | IF=-12A,dI/dt=100A/μs, | | 16 | | nC |

Note:

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,t<10sec.
- 2.The data tested by pulsed , pulse width ≤ 300 us , duty cycle $\leq 2\%$
- 3. The EAS data shows Max. rating . The test condition is V_{DD} =-25V, V_{GS} =-10V, L=0.1mH, I_{AR} =-12A
- 4. The power dissipation is limited by 150 ℃ junction temperature
- 5.The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

Figure 1. Power Dissipation

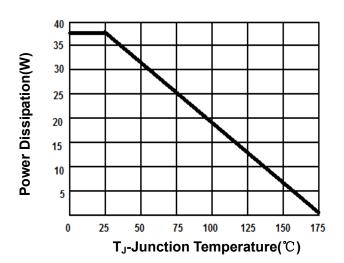


Figure 3. Output Characteristics

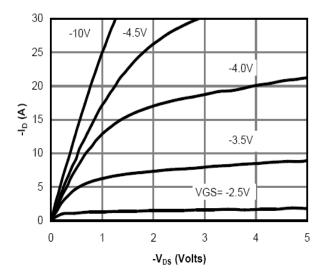


Figure 2. Drain Current

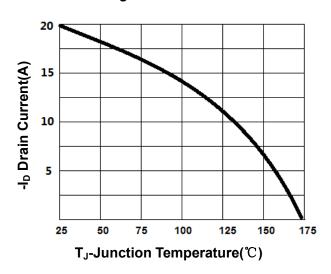
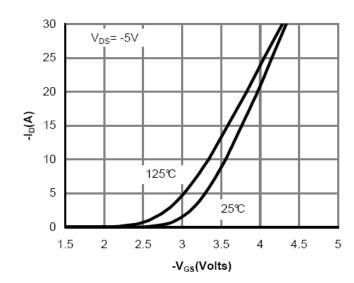


Figure 4. Transfer Characteristics





Typical Characteristics

Figure 5. Capacitance

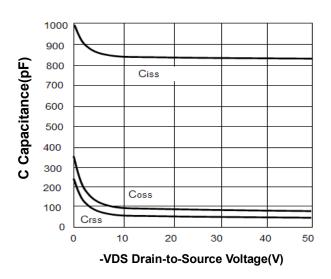


Figure 6. R_{DS(ON)} vs Junction Temperature

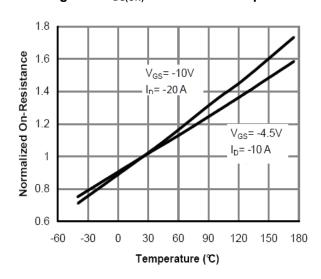


Figure 7. V_{GS(th)} vs Junction Temperature

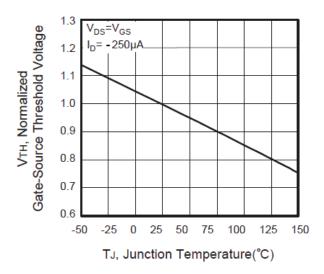
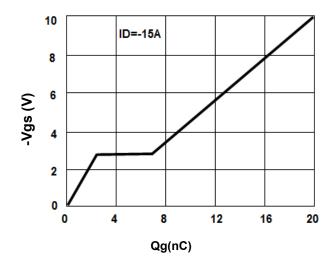


Figure8. Gate Charge Waveforms





Typical Characteristics

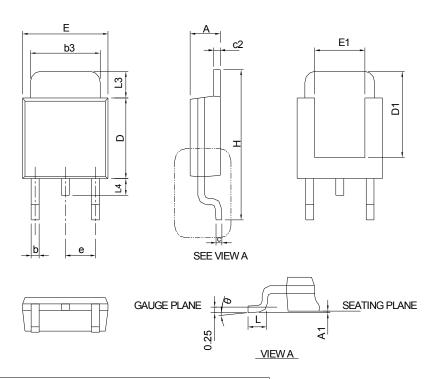
10 In descending order $D=T_{on}/T$ Z_{eJC} Normalized Transient D=0.5, 0.3, 0.1, 0.05, 0.02, 0.01, single pulse $T_{J,PK}=T_C+P_{DM}.Z_{\theta JC}.R_{\theta JC}$ Thermal Resistance 1 0.1 Single Pulse 0.01 0.00001 0.0001 0.001 0.01 0.1 10 100

Pulse Width (s)

Figure 9. Normalized Maximum Transient Thermal Impedance

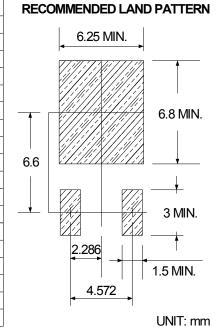


D-Pak (TO-252AA) (TO-252) (TO-252-3L) Package Outline (Dimensions are shown in millimeters (inches))



| ş | TO-252-3L | | | | |
|-----------------|-------------|-------|--------|-------|--|
| <i>o</i> ≥=2mO_ | MILLIMETERS | | INCHES | | |
| Б | MIN. | MAX. | MIN. | MAX. | |
| Α | 2.18 | 2.39 | 0.086 | 0.094 | |
| A1 | - | 0.13 | - | 0.005 | |
| b | 0.50 | 0.89 | 0.020 | 0.035 | |
| b3 | 4.95 | 5.46 | 0.195 | 0.215 | |
| С | 0.46 | 0.61 | 0.018 | 0.024 | |
| c2 | 0.46 | 0.89 | 0.018 | 0.035 | |
| D | 5.33 | 6.22 | 0.210 | 0.245 | |
| D1 | 4.57 | 6.00 | 0.180 | 0.236 | |
| Е | 6.35 | 6.73 | 0.250 | 0.265 | |
| E1 | 3.81 | 6.00 | 0.150 | 0.236 | |
| е | 2.29 BSC | | 0.09 | 0 BSC | |
| Н | 9.40 | 10.41 | 0.370 | 0.410 | |
| L | 0.90 | 1.78 | 0.035 | 0.070 | |
| L3 | 0.89 | 2.03 | 0.035 | 0.080 | |
| L4 | - | 1.02 | - | 0.040 | |
| θ | 0° | 8° | 0° | 8° | |

Note: Follow JEDEC TO-252.





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